# CPI1008J3R3R-10

# UNCONTROLLED DOCUMENT

## PHYSICAL DIMENSIONS:

5

Inductance(uH)

Inductance(uH)

0

0.1

A  $2.50 [.098] \pm 0.20[.008]$ 

B 2.00 [.079] ± 0.20[.008]

C 0.90 [.035] ± 0.10[.004]

D 0.60 [.024] ± 0.20[.008]

10

Ls vs Frequency

Frequency (MHz)

Ls vs DC BIAS Current

0.4

0.6

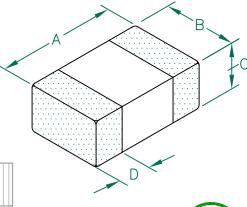
DC BIAS Current (A)

0.8

100

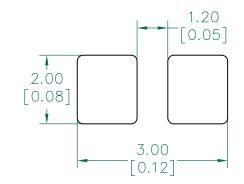
1.000

1.2





#### LAND PATTERNS FOR REFLOW SOLDERING



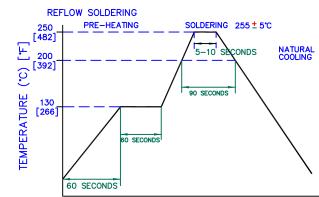
(For wave soldering. add 0.763 [0.030] to this dimension)

ELECTRICAL CHARACTERISTICS:									
	L (μΗ) @ 1MHz ± 20%	DCR ( $\frac{\Omega}{2}$ ) ± 25%	l (Max)						
Nom	3.30	0.1600							
Min	2.64	0.1200							
Max	3.96	0.2000	1200mA						

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

### RECOMMENDED SOLDERING CONDITIONS





	DIMENSIONS ARE IN mm [INCHE		This print is the property of Lair						
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С	UPDATE PAD DIMENSION ROHS	07/08/14	QU	CPI1008J3R3R-10		C	CO-	-FIRE	QU
В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11	SCA	LE: N	TS	SHEET:	1
Α	ORIGINAL DRAFT	03/01/11	QU	CAD #	TOO		13		
REV	DESCRIPTION	DATE	INT	CPI1008J3R3R-10-C			_	1	of 1